

Claims

- [c1] 1. A method of fabricating an active matrix organic light emitting diode, comprising:
- providing a substrate having a display area and a non-display area thereon, wherein the display area comprises a plurality of pixel structures thereon;
 - forming a plurality of transparent conductive lines electrically connected to the pixel structures and extending from the display area towards the non-display area;
 - disposing a cap over the substrate to cover the display area;
 - applying a photosensitive glue at a perimeter of the display area between the cap and the substrate, so that the cap is adhered to the substrate thereby;
 - performing a radiation step to cure the photosensitive glue; and
 - forming a driving chip in the non-display area of the substrate, wherein the driving chip is electrically connected to the pixel structures via the transparent conductive lines.
- [c2] 2. The method according to Claim 1, wherein the transparent conductive line is made of indium tin oxide or in-

dium zinc oxide.

- [c3] 3. The method according to Claim 1, wherein the transparent conductive line has a length of about 2mm to about 4mm.
- [c4] 4. The method according to Claim 1, wherein the photo-sensitive glue includes an ultra-violet glue.
- [c5] 5. The method according to Claim 4, wherein the radiation step further comprises an ultra-violet radiation step.
- [c6] 6. The method according to Claim 5, wherein the cap includes metal cap or a glass cap.